ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				erials and l	ials and Mfg Information				
upplier Informa	ation				·										
Company name*			Company unique ID			τ	Unique ID Authority				Respo	Response Date*			
nsemi										2023-0	2023-06-07				
Contact Name			Title - Contact			1	Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewar	rds		Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized Represen	ntative*	Title - Representative			I	Phone - Representative*				Email	Email - Representative*				
Product-Env-Stewar	rds	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Requester	Requester Item Number		Mfr Item Number Mfr Item Nam		ie		Effective Dat	e Versi	on	Manufacturing Site		Weight*	UOM	Unit Type	
		NCV8141D2TR4G ANA W		ANA WATCHDO	NA WATCHDOG REGULATOR		2023-06-07 MY1		MY1 1		1421.5	mg	Each		
Ianufacturing F	Proccess Information	on						,							
Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temperature		re Max Time at Pe	ak Temper	ature Numb	er of Reflow Cyc	eles			
Matte Tin (Sn) - annealed			CU Alloy 3			260 C 30		30	seco	onds 3					
omments															
TTENTION: MSL	3 Rated item requires E	Bake and D	ry Pack (after	r electrical test)											
or more information	n regarding material co	mposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.34	mg	A	Lead (Pb)	7439-92-1	7a	10.773	mg
			Supplier	Tin (Sn)	7440-31-5		0.567	mg
Lead Frame	851.91	mg	В	Nickel (Ni)	7440-02-0		2.5557	mg
			Supplier	Copper (Cu)	7440-50-8		849.3542	mg
Mold Compound-Black	529.31	mg		Epoxy Phenol Resin	proprietary data		55.5775	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		473.7325	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Au	1.6	mg	Supplier	Gold (Au)	7440-57-5		1.6	mg